



VP800

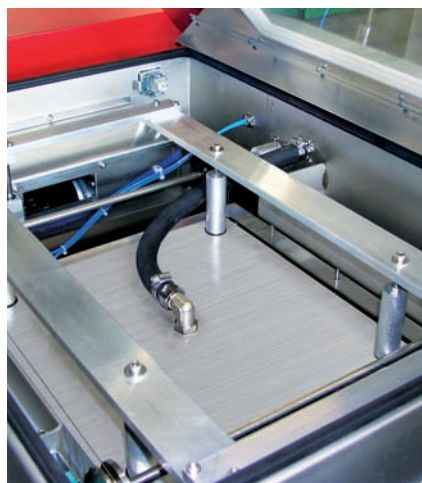
VACUUM

Vacuummodule – Upgrade for VP800

Vacuum process for vapour-phase reflow soldering worldwide for the first time developed and patented by ASSCON is now also available for ASSCON laboratory-reflow soldering systems. The process is based on the vacuum technology which has proved itself in the ASSCON vapour-phase reflow soldering systems for batch and mass production for years.

The brand new vacuum module is designed for ASSCON VP800 reflow soldering system, being used worldwide in laboratories, prototyping, research & development, training and universities with very great success for years. The vacuum unit is designed as a monobloc technique unit, which contains at the same time the vacuum module and the cooling module of the reflow soldering system.

The modular design of the upgrade unit enables customers to upgrade their existing VP800 vapour-phase soldering system.



Evacuation unit

Highlights

- Adjustable vacuum ensures ideal void-free solder joints
- Easy activation and deactivation of vacuum process ensures an maximum of flexibility in production
- Monobloc technique unit ensures space-saving installation

Typical Applications

- Laboratory
- Prototyping, Small batch series
- Close-to-production process qualification
- Research & Development
- Training, University

Technical Data

Maximum solder piece format	320 x 300 mm
Maximum solder piece height	55 mm
Connected load reflow soldering unit	5,5 kW
Connected load technique unit	3,0 kW